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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

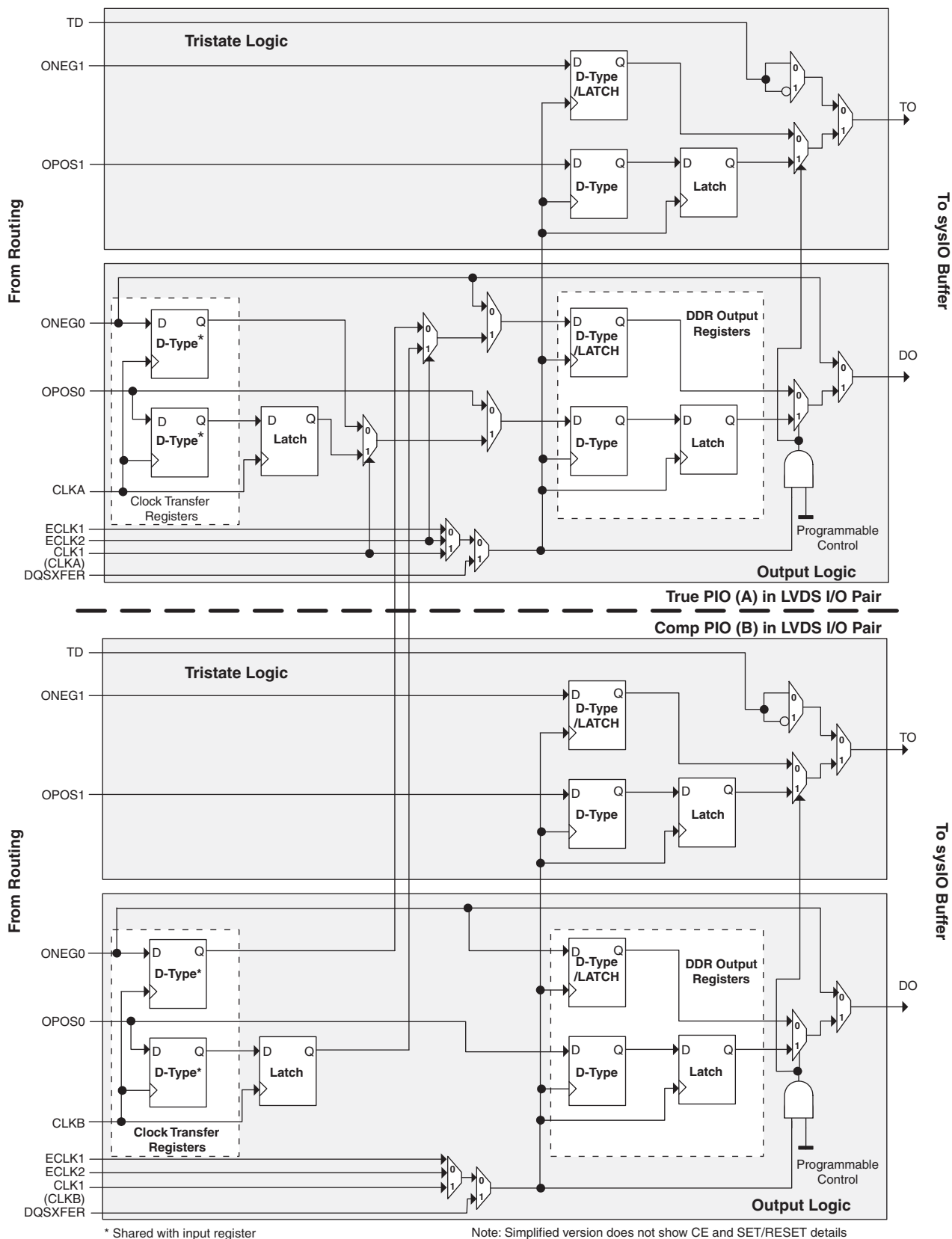
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	4246528
Number of I/O	270
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m50e-6fn484c

Figure 2-31. Output and Tristate Block for Left, Right and Bottom Edges

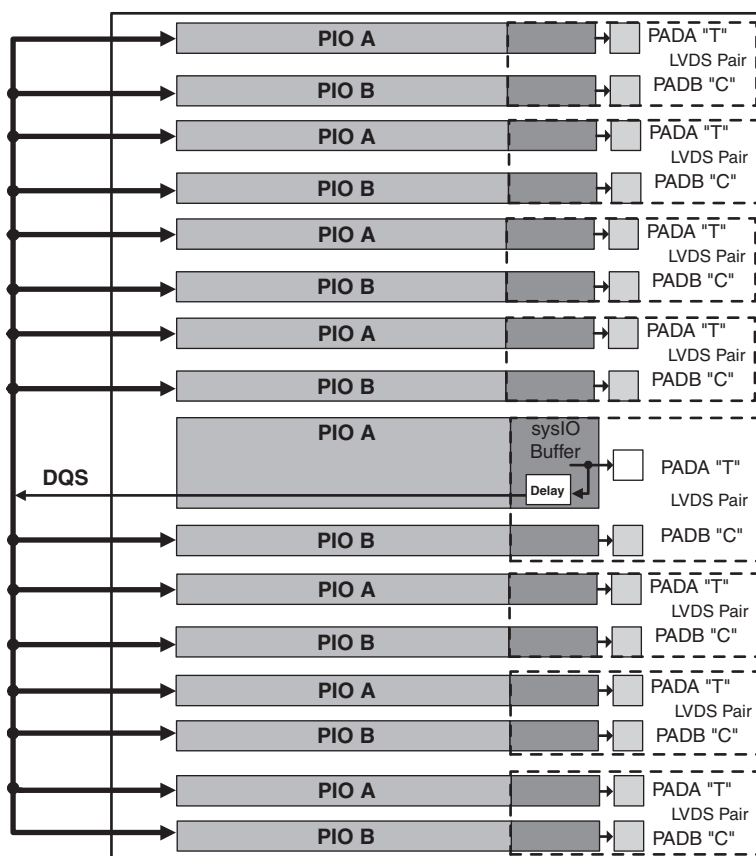


Top Edge

The PICs on the top edge are different from PIOs on the left, right and bottom edges. PIOs on this edge do not have DDR registers or DQS signals.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. Interfaces on the left and right edges are designed for DDR memories that support 16 bits of data, whereas interfaces on the bottom are designed for memories that support 18 bits of data.

Figure 2-33. DQS Input Routing for the Left and Right Edges of the Device



DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	210	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
$C1^4$	I/O Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
$C2^4$	Dedicated Input Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF} maximum leakage = 25 μA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, $f = 1.0MHz$.

Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-7 Timing	Units
Basic Functions		
16-bit Decoder	3.8	ns
32-bit Decoder	4.5	ns
64-bit Decoder	5.0	ns
4:1 MUX	3.2	ns
8:1 MUX	3.4	ns
16:1 MUX	3.5	ns
32:1 MUX	4.0	ns

1. These timing numbers were generated using the ispLEVER 8.0 design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Register-to-Register Performance

Function	-7 Timing	Units
Basic Functions		
16-bit Decoder	599	MHz
32-bit Decoder	542	MHz
64-bit Decoder	417	MHz
4:1 MUX	847	MHz
8:1 MUX	803	MHz
16:1 MUX	660	MHz
32:1 MUX	577	MHz
8-bit Adder	591	MHz
16-bit Adder	500	MHz
64-bit Adder	306	MHz
16-bit Counter	488	MHz
32-bit Counter	378	MHz
64-bit Counter	260	MHz
64-bit Accumulator	253	MHz
Embedded Memory Functions		
512x36 Single Port RAM, EBR Output Registers	370	MHz
1024x18 True-Dual Port RAM (Write Through or Normal, EBR Output Registers)	370	MHz
1024x18 True-Dual Port RAM (Write Through or Normal, PLC Output Registers)	280	MHz
Distributed Memory Functions		
16x4 Pseudo-Dual Port RAM (One PFU)	819	MHz
32x4 Pseudo-Dual Port RAM	521	MHz
64x8 Pseudo-Dual Port RAM	435	MHz
DSP Functions		
18x18 Multiplier (All Registers)	420	MHz
9x9 Multiplier (All Registers)	420	MHz

LatticeECP2/M Family Timing Adders^{1, 2, 3}
Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
Input Adjusters					
LVDS25	LVDS	-0.04	-0.02	0.00	ns
BLVDS25	BLVDS	-0.04	-0.09	-0.15	ns
MLVDS	LVDS	-0.15	-0.15	-0.15	ns
RSDS	RSDS	-0.15	-0.15	-0.15	ns
LVPECL33	LVPECL	0.16	0.15	0.13	ns
HSTL18_I	HSTL_18 class I	0.01	-0.01	-0.04	ns
HSTL18_II	HSTL_18 class II	0.01	-0.01	-0.04	ns
HSTL18D_I	Differential HSTL 18 class I	0.01	-0.01	-0.04	ns
HSTL18D_II	Differential HSTL 18 class II	0.01	-0.01	-0.04	ns
HSTL15_I	HSTL_15 class I	0.01	-0.01	-0.04	ns
HSTL15D_I	Differential HSTL 15 class I	0.01	-0.01	-0.04	ns
SSTL33_I	SSTL_3 class I	-0.03	-0.07	-0.10	ns
SSTL33_II	SSTL_3 class II	-0.03	-0.07	-0.10	ns
SSTL33D_I	Differential SSTL_3 class I	-0.03	-0.07	-0.10	ns
SSTL33D_II	Differential SSTL_3 class II	-0.03	-0.07	-0.10	ns
SSTL25_I	SSTL_2 class I	-0.04	-0.07	-0.10	ns
SSTL25_II	SSTL_2 class II	-0.04	-0.07	-0.10	ns
SSTL25D_I	Differential SSTL_2 class I	-0.04	-0.07	-0.10	ns
SSTL25D_II	Differential SSTL_2 class II	-0.04	-0.07	-0.10	ns
SSTL18_I	SSTL_18 class I	-0.01	-0.04	-0.07	ns
SSTL18_II	SSTL_18 class II	-0.01	-0.04	-0.07	ns
SSTL18D_I	Differential SSTL_18 class I	-0.01	-0.04	-0.07	ns
SSTL18D_II	Differential SSTL_18 class II	-0.01	-0.04	-0.07	ns
LVTTTL33	LVTTTL	-0.16	-0.16	-0.16	ns
LVC MOS33	LVC MOS 3.3	-0.08	-0.12	-0.16	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	-0.16	-0.17	-0.17	ns
LVC MOS15	LVC MOS 1.5	-0.14	-0.14	-0.14	ns
LVC MOS12	LVC MOS 1.2	-0.04	-0.01	0.01	ns
PCI33	PCI	-0.08	-0.12	-0.16	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E ⁴	0.25	0.19	0.13	ns
LVDS25	LVDS 2.5	0.10	0.13	0.17	ns
BLVDS25	BLVDS 2.5	0.00	-0.01	-0.03	ns
MLVDS	MLVDS 2.5 ⁴	0.00	-0.01	-0.03	ns
RSDS	RSDS 2.5 ⁴	0.25	0.19	0.13	ns
LVPECL33	LVPECL 3.3 ⁴	-0.02	-0.04	-0.06	ns
HSTL18_I	HSTL_18 class I 8mA drive	-0.19	-0.22	-0.25	ns
HSTL18_II	HSTL_18 class II	-0.30	-0.34	-0.37	ns
HSTL18D_I	Differential HSTL 18 class I 8mA drive	-0.19	-0.22	-0.25	ns
HSTL18D_II	Differential HSTL 18 class II	-0.30	-0.34	-0.37	ns

SERDES External Reference Clock (LatticeECP2M Family Only)

The external reference clock selection and its interface are a critical part of system applications for this product. Table 3-14 specifies reference clock requirements, over the full range of operating conditions.

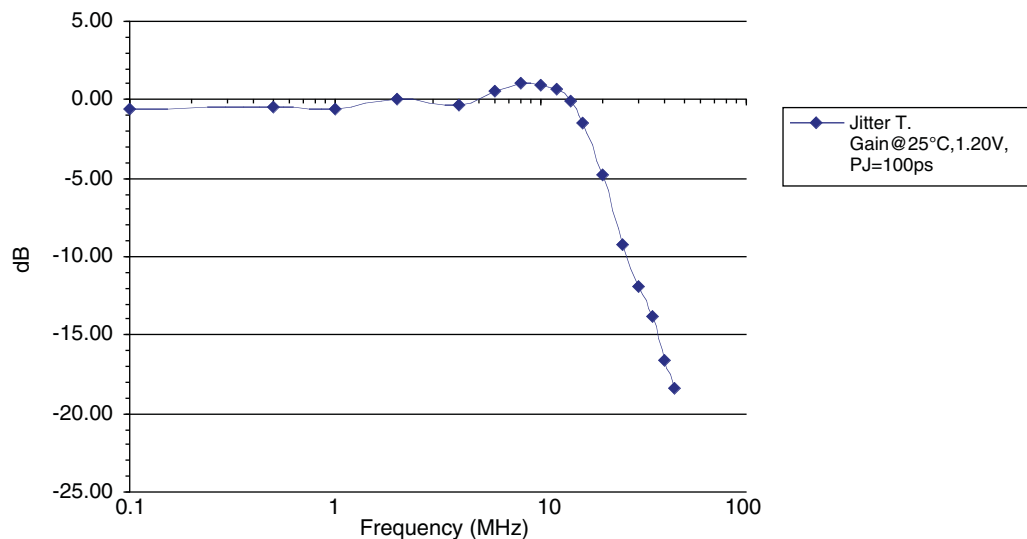
Table 3-14. External Reference Clock Specification (refclkp/refclkn)

Symbol	Description	Min.	Typ.	Max.	Units
F _{REF}	Frequency range	25	—	320	MHz
F _{REF-PPM}	Frequency tolerance	-300	—	300	ppm
V _{REF-IN-SE}	Input swing, single-ended clock ¹	100	—	1200	mV, p-p
V _{REF-IN}	Input levels	0	—	V _{CCP} + 0.8	V
V _{REF-CM-DC}	Input common mode range (DC coupled)	0.5	—	1.2	V
V _{REF-CM-AC}	Input common mode range (AC coupled) ²	0	—	1.5	V
D _{REF}	Duty cycle ³	40	—	60	%
T _{REF-R}	Rise time (20% to 80%)		500	1000	ps
T _{REF-F}	Fall time (80% to 20%)		500	1000	ps
Z _{REF-IN-TERM}	Input termination		50/2K		Ohms
C _{REF-IN-CAP}	Input capacitance ⁴	—	—	1.5	pF

1. The signal swing for a single-ended input clock must be as large as the p-p differential swing of a differential input clock to get the same gain at the input receiver. Lower swings for the clock may be possible, but will tend to increase jitter.
2. When AC coupled, the input common mode range is determined by:

$$(\text{Min input level}) + (\text{Peak-to-peak input swing})/2 \leq (\text{Input common mode voltage}) \leq (\text{Max input level}) - (\text{Peak-to-peak input swing})/2$$
3. Measured at 50% amplitude.
4. Input capacitance of 1.5pF is total capacitance, including both device and package.

Figure 3-13. Jitter Transfer



Note: This graph is for a nominal device.

SERDES Power-Down/Power-Up Specification

Table 3-15. Power-Down and Power-Up Specification

Symbol	Description	Max.	Units
t _{PWRDN}	Power-down time after all power down register bits set to '0'	10	μs
t _{PWRUP}	Power-up time after all power down register bits set to '1'	100	μs

PCI Express Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-16. Transmit^{1, 2}

Symbol	Description	Test Conditions	Min	Typ	Max	Units
UI	Unit interval		399.88	400	400.12	ps
V _{TX-DIFF_P-P}	Differential peak-to-peak output voltage		0.8	1.0	1.2	V
V _{TX-DE-RATIO}	De-emphasis differential output voltage ratio		0	-3.5	-7.96	dB
V _{TX-CM-AC_P}	RMS AC peak common-mode output voltage		—	20	—	mV
V _{TX-CM-DC-LINE-DELTA}	Maximum Common mode voltage delta between n and p channels		—	—	25	mV
V _{TX-DC-CM}	Tx DC common mode voltage		0	—	V _{CCOB} + 5%	V
I _{TX-SHORT}	Output short circuit current	V _{TX-D+} =0.0V V _{TX-D-} =0.0V	—	—	90	mA
Z _{TX-DIFF-DC}	Differential output impedance		80	100	120	Ohms
T _{TX-RISE}	Tx output rise time	20 to 80%	0.125	—	—	UI
T _{TX-FALL}	Tx output fall time	20 to 80%	0.125	—	—	UI
L _{TX-SKEW}	Lane-to-lane static output skew for all lanes in port/link		—	—	1.3	ns
T _{TX-EYE}	Transmitter eye width		0.75	—	—	UI
T _{TX-EYE-MEDIAN-TO-MAX-JITTER} ³			—	—	0.125	UI
C _{TX}	AC coupling capacitor		75	—	200	nF

1. Values are measured at 2.5 Gbps.

2. Compliant to PCI Express v1.1.

3. Measured at 60ps with plug-in board and jitter due to socket removed.

Table 3-17. Receive

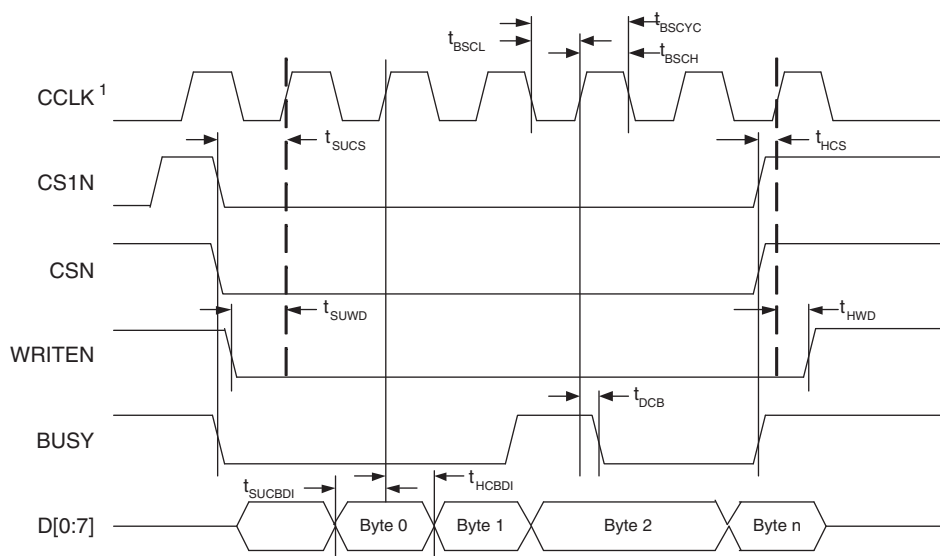
Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
UI	Unit Interval		399.88	400	400.12	ps
V _{RX-DIFF_P-P}	Differential peak-to-peak input voltage		0.175	—	—	V
V _{RX-IDLE-DET-DIFF_P-P}	Idle detect threshold voltage		65	—	175	mV
Z _{RX-DIFF-DC}	DC differential input impedance		80	100	120	Ohms
Z _{RX-DC}	DC input impedance		40	50	60	Ohms
Z _{RX-HIGH-IMP-DC} ¹	Power-down DC input impedance		200K	—	—	Ohms
T _{RX-EYE}	Receiver eye width		0.4	—	—	UI
T _{RX-EYE-MEDIAN-TO-MAX-JITTER}			—	—	0.3	UI

Notes:

1. Measured with external AC-coupling on the receiver

2. Values are measured at 2.5 Gbps

Figure 3-15. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-16. sysCONFIG Slave Serial Port Timing

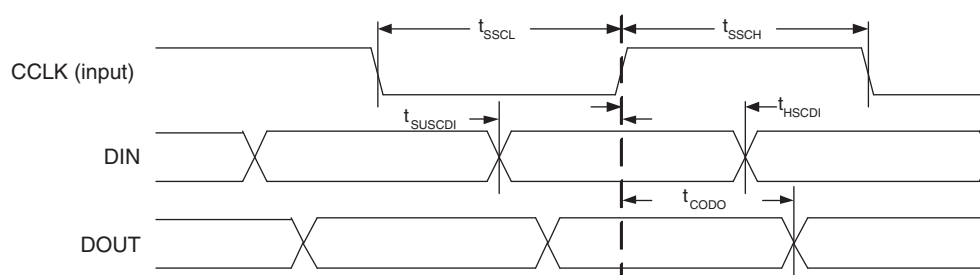
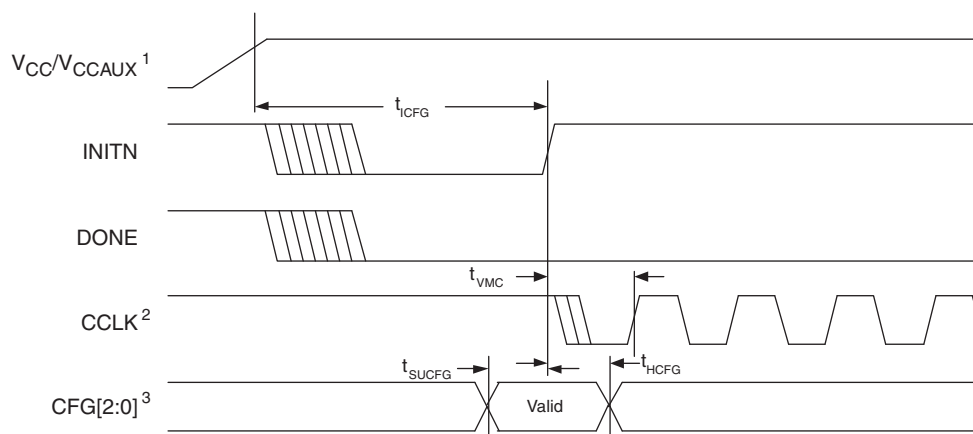


Figure 3-17. Power-On-Reset (POR) Timing



1. Time taken from V_{CC} or V_{CCAUX} , whichever is the last to reach its V_{MIN} .
2. Device is in a Master Mode.
3. The CFG pins are normally static (hard wired).

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
138	PR15A	3	PCLKT3_0	T (LVDS)*	PR21A	3	PCLKT3_0/RDQ25	T (LVDS)*	
139	GND	-			GND	-			
140	VCC	-			VCC	-			
141	PR13B	2	PCLKC2_0/RDQ10	C	PR19B	2	PCLKC2_0/RDQ16	C	
142	PR13A	2	PCLKT2_0/RDQ10	T	PR19A	2	PCLKT2_0/RDQ16	T	
143	VCCIO2	2			VCCIO2	2			
144	PR12A	2	RDQ10		PR16A	2	RDQS16		
145	GND	-			GND	-			
146	VCC	-			VCC	-			
147	PR8B	2	RDQ10	C (LVDS)*	PR14B	2	RDQ16	C (LVDS)*	
148	VCCIO2	2			VCCIO2	2			
149	PR8A	2	RDQ10	T (LVDS)*	PR14A	2	RDQ16	T (LVDS)*	
150	PR6B	2	RDQ10	C (LVDS)*	PR12B	2	RDQ16	C (LVDS)*	
151	VCCAUX	-			VCCAUX	-			
152	PR6A	2	RDQ10	T (LVDS)*	PR12A	2	RDQ16	T (LVDS)*	
153	PR4B	2		C (LVDS)*	PR6B	2	RDQ8	C (LVDS)*	
154	PR4A	2		T (LVDS)*	PR6A	2	RDQ8	T (LVDS)*	
155	PR2B	2	VREF2_2	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*	
156	PR2A	2	VREF1_2	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*	
157	PT55B	1	VREF2_1	C	PT64B	1	VREF2_1	C	
158	PT55A	1	VREF1_1	T	PT64A	1	VREF1_1	T	
159	GND	-			GND	-			
160	PT54B	1		C	PT62B	1		C	
161	PT54A	1		T	PT62A	1		T	
162	VCCIO1	1			VCCIO1	1			
163	PT52B	1		C	PT60B	1		C	
164	PT52A	1		T	PT60A	1		T	
165	PT50B	1		C	PT58B	1		C	
166	PT50A	1		T	PT58A	1		T	
167	PT48B	1		C	PT56B	1		C	
168	PT48A	1		T	PT56A	1		T	
169	GND	-			GND	-			
170	VCCIO1	1			VCCIO1	1			
171	VCC	-			VCC	-			
172	PT40B	1		C	PT50B	1		C	
173	PT40A	1		T	PT50A	1		T	
174	VCCAUX	-			VCCAUX	-			
175	GND	-			GND	-			
176	PT36B	1		C	PT44B	1		C	
177	PT36A	1		T	PT44A	1		T	
178	PT34B	1		C	PT42B	1		C	
179	PT34A	1		T	PT42A	1		T	
180	PT30B	1	PCLKC1_0	C	PT39B	1	PCLKC1_0	C	
181	PT30A	1	PCLKT1_0	T	PT39A	1	PCLKT1_0	T	
182	XRES	1			XRES	1			
183	PT28B	0	PCLKC0_0	C	PT37B	0	PCLKC0_0	C	

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO6	-			GNDIO6	-		
L2	PL24A	6	LDQ28	T (LVDS)*	PL24A	6	LDQ28	T (LVDS)*
K2	PL25A	6	LDQ28	T	PL25A	6	LDQ28	T
L3	PL24B	6	LDQ28	C (LVDS)*	PL24B	6	LDQ28	C (LVDS)*
K1	PL25B	6	LDQ28	C	PL25B	6	LDQ28	C
VCCIO	VCCIO6	6			VCCIO6	6		
L4	PL26A	6	LDQ28	T (LVDS)*	PL26A	6	LDQ28	T (LVDS)*
L1	PL27A	6	LDQ28	T	PL27A	6	LDQ28	T
L5	PL26B	6	LDQ28	C (LVDS)*	PL26B	6	LDQ28	C (LVDS)*
M1	PL27B	6	LDQ28	C	PL27B	6	LDQ28	C
GND	GNDIO6	-			GNDIO6	-		
N1	PL29A	6	LDQ28	T	PL29A	6	LDQ28	T
N2	PL28A	6	LDQS28	T (LVDS)*	PL28A	6	LDQS28	T (LVDS)*
P1	PL29B	6	LDQ28	C	PL29B	6	LDQ28	C
VCCIO	VCCIO6	6			VCCIO6	6		
P2	PL28B	6	LDQ28	C (LVDS)*	PL28B	6	LDQ28	C (LVDS)*
R1	PL30A	6	LDQ28	T (LVDS)*	PL30A	6	LDQ28	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
R2	PL30B	6	LDQ28	C (LVDS)*	PL30B	6	LDQ28	C (LVDS)*
N4	TDI	-			TDI	-		
M4	TCK	-			TCK	-		
P3	TDO	-			TDO	-		
N3	TMS	-			TMS	-		
K7	VCCJ	-			VCCJ	-		
M5	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
K6	NC	-			PB3A	5	BDQ6	
M6	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
R3	NC	-			PB5A	5	BDQ6	T
P4	NC	-			PB5B	5	BDQ6	C
-	-	-			VCCIO	5		
-	-	-			GNDIO5	5		
N5	PB3A	5	BDQ6	T	PB21A	5	BDQ24	T
N6	PB3B	5	BDQ6	C	PB21B	5	BDQ24	C
T2	PB4A	5	BDQ6	T	PB22A	5	BDQ24	T
P6	PB5A	5	BDQ6	T	PB23A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
T3	PB4B	5	BDQ6	C	PB22B	5	BDQ24	C
R6	PB5B	5	BDQ6	C	PB23B	5	BDQ24	C
GND	GNDIO5	-			GNDIO5	-		
R4	PB6A	5	BDQS6	T	PB24A	5	BDQS24	T
L6	PB7A	5	BDQ6	T	PB25A	5	BDQ24	T
T4	PB6B	5	BDQ6	C	PB24B	5	BDQ24	C
L7	PB7B	5	BDQ6	C	PB25B	5	BDQ24	C
N7	PB8A	5	PCLKT5_0/BDQ6	T	PB26A	5	PCLKT5_0/BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G24	PR6B	2	RDQ8	C (LVDS)*	PR12B	2	RDQ14	C (LVDS)*
G23	PR6A	2	RDQ8	T (LVDS)*	PR12A	2	RDQ14	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
K19	PR5B	2	RDQ8	C	PR11B	2	RDQ14	C
J19	PR5A	2	RDQ8	T	PR11A	2	RDQ14	T
D26	PR4B	2	RDQ8	C (LVDS)*	PR10B	2	RDQ14	C (LVDS)*
C26	PR4A	2	RDQ8	T (LVDS)*	PR10A	2	RDQ14	T (LVDS)*
F22	NC	-			PR9B	2	RDQ6	C
E24	NC	-			PR9A	2	RDQ6	T
GND	GNDIO2	-			GNDIO2	-		
D25	NC	-			PR8B	2	RDQ6	C (LVDS)*
C25	NC	-			PR8A	2	RDQ6	T (LVDS)*
D24	NC	-			PR7B	2	RDQ6	C
B25	NC	-			PR7A	2	RDQ6	T
VCCIO	VCCIO2	2			VCCIO2	2		
H21	NC	-			PR6B	2	RDQ6	C (LVDS)*
G22	NC	-			PR6A	2	RDQS6	T (LVDS)*
B24	NC	-			PR5B	2	RDQ6	C
GND	GNDIO2	-			GNDIO2	-		
C24	NC	-			PR5A	2	RDQ6	T
D23	NC	-			PR4B	2	RDQ6	C (LVDS)*
C23	NC	-			PR4A	2	RDQ6	T (LVDS)*
G21	PR3B	2		C	PR3B	2	RDQ6	C
VCCIO	VCCIO2	2			VCCIO2	2		
H20	PR3A	2		T	PR3A	2	RDQ6	T
GND	GNDIO2	-			GNDIO2	-		
E22	PR2B	2	VREF2_2	C (LVDS)*	PR2B	2	VREF2_2/RDQ6	C (LVDS)*
F21	PR2A	2	VREF1_2	T (LVDS)*	PR2A	2	VREF1_2/RDQ6	T (LVDS)*
E23	PT64B	1	VREF2_1	C	PT73B	1	VREF2_1	C
GND	GNDIO1	-			GNDIO1	-		
D22	PT64A	1	VREF1_1	T	PT73A	1	VREF1_1	T
G20	PT63B	1		C	PT72B	1		C
J18	PT63A	1		T	PT72A	1		T
F20	PT62B	1		C	PT71B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H19	PT62A	1		T	PT71A	1		T
A24	PT61B	1		C	PT70B	1		C
A23	PT61A	1		T	PT70A	1		T
E21	PT60B	1		C	PT69B	1		C
F19	PT60A	1		T	PT69A	1		T
C22	PT59B	1		C	PT68B	1		C
GND	GNDIO1	-			GNDIO1	-		
E20	PT59A	1		T	PT68A	1		T
B22	PT58B	1		C	PT67B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
B23	PT58A	1		T	PT67A	1		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
P3	PL54B	7	LDQ54	C (LVDS)*
R6	PL55A	7	LDQ54	T
VCCIO	VCCIO7	7		
R8	PL55B	7	LDQ54	C
P2	PL56A	7	LDQ54	T (LVDS)*
P1	PL56B	7	LDQ54	C (LVDS)*
R5	PL57A	7	PCLKT7_0/LDQ54	T
GND	GNDIO7	-		
R7	PL57B	7	PCLKC7_0/LDQ54	C
R4	PL59A	6	PCLKT6_0/LDQ63	T (LVDS)*
R3	PL59B	6	PCLKC6_0/LDQ63	C (LVDS)*
T5	PL60A	6	VREF2_6/LDQ63	T
T7	PL60B	6	VREF1_6/LDQ63	C
T3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
T4	PL61B	6	LDQ63	C (LVDS)*
T6	PL62A	6	LDQ63	T
T8	PL62B	6	LDQ63	C
T2	PL63A	6	LDQS63	T (LVDS)*
GND	GNDIO6	-		
T1	PL63B	6	LDQ63	C (LVDS)*
U7	PL64A	6	LDQ63	T
U5	PL64B	6	LDQ63	C
VCCIO	VCCIO6	6		
U4	PL65A	6	LDQ63	T (LVDS)*
U3	PL65B	6	LDQ63	C (LVDS)*
U8	PL66A	6	LDQ63	T
U6	PL66B	6	LDQ63	C
GND	GNDIO6	-		
U2	PL67A	6	LDQ71	T (LVDS)*
U1	PL67B	6	LDQ71	C (LVDS)*
V7	PL68A	6	LDQ71	T
V5	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6		
V2	PL69A	6	LDQ71	T (LVDS)*
V1	PL69B	6	LDQ71	C (LVDS)*
V8	PL70A	6	LDQ71	T
V6	PL70B	6	LDQ71	C
GND	GNDIO6	-		
W1	PL71A	6	LDQS71	T (LVDS)*
W2	PL71B	6	LDQ71	C (LVDS)*
W5	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AB24	PR87B	8	D3	C
GND	GNDIO4	-		
AB23	PR87A	8	D4	T
AB25	PR86B	8	D5	C
AB26	PR86A	8	D6	T
AC27	PR85B	8	D7/SPID0	C
VCCIO	VCCIO8	8		
AB27	PR85A	8	DI/CSSPION	T
AD29	PR84B	8	DOUT/CSON	C
AD30	PR84A	8	BUSY/SISPI	T
AA25	PR83B	3	RDQ80	C
GND	GNDIO3	-		
AA23	PR83A	3	RDQ80	T
AC29	PR82B	3	RDQ80	C (LVDS)*
AC30	PR82A	3	RDQ80	T (LVDS)*
AA26	PR81B	3	RDQ80	C
VCCIO	VCCIO3	3		
AA24	PR81A	3	RDQ80	T
AB29	PR80B	3	RDQ80	C (LVDS)*
AB30	PR80A	3	RDQS80	T (LVDS)*
GND	GNDIO3	-		
Y23	PR79B	3	RDQ80	C
Y25	PR79A	3	RDQ80	T
AA27	PR78B	3	RDQ80	C (LVDS)*
AA28	PR78A	3	RDQ80	T (LVDS)*
VCCIO	VCCIO3	3		
Y24	PR77B	3	RLM0_GPLL_C_FB_A/RDQ80	C
Y26	PR77A	3	RLM0_GPLLT_FB_A/RDQ80	T
AA29	PR76B	3	RLM0_GPLL_C_IN_A**/RDQ80	C (LVDS)*
AA30	PR76A	3	RLM0_GPLLT_IN_A**/RDQ80	T (LVDS)*
R22	RLM0_PLLCAP	3		
W23	PR74B	3	RLM0_GDLL_C_FB_A/RDQ71	C
W25	PR74A	3	RLM0_GDLLT_FB_A/RDQ71	T
GND	GNDIO3	-		
Y27	PR73B	3	RLM0_GDLL_C_IN_A**/RDQ71	C (LVDS)*
Y28	PR73A	3	RLM0_GDLLT_IN_A**/RDQ71	T (LVDS)*
W24	PR72B	3	RDQ71	C
W26	PR72A	3	RDQ71	T
VCCIO	VCCIO3	3		
Y29	PR71B	3	RDQ71	C (LVDS)*
Y30	PR71A	3	RDQS71	T (LVDS)*
V25	PR70B	3	RDQ71	C
GND	GNDIO3	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
F20	PR30A	2	RDQ27	T
GNDIO	GNDIO2	-		
G17	PR29B	2	RDQ27	C (LVDS)*
F17	PR29A	2	RDQ27	T (LVDS)*
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E22	PR14B	2		C
D22	PR14A	2		T
VCCIO	VCCIO2	-		
E20	PR13B	2		C (LVDS)*
D20	PR13A	2		T (LVDS)*
D19	PR12B	2	RUM0_SPLLC_FB_A	C
GNDIO	GNDIO2	-		
E19	PR12A	2	RUM0_SPLLT_FB_A	T
F18	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*
F19	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*
VCCIO	VCCIO2	-		
E18	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-		
D18	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2		
F16	XRES	-		
C22	URC_SQ_VCCR0	12		
A21	URC_SQ_HDINP0	12		T
B22	URC_SQ_VCCIB0	12		
B21	URC_SQ_HDINN0	12		C
C19	URC_SQ_VCCTX0	12		
A18	URC_SQ_HDOUTP0	12		T
A19	URC_SQ_VCCOB0	12		
B18	URC_SQ_HDOUTN0	12		C
C18	URC_SQ_VCCTX1	12		
B17	URC_SQ_HDOUTN1	12		C
C17	URC_SQ_VCCOB1	12		
A17	URC_SQ_HDOUTP1	12		T
C21	URC_SQ_VCCR1	12		
B20	URC_SQ_HDINN1	12		C
C20	URC_SQ_VCCIB1	12		
A20	URC_SQ_HDINP1	12		T
B16	URC_SQ_VCCAUX33	12		
E17	URC_SQ_REFCLKN	12		C
D17	URC_SQ_REFCLKP	12		T
C16	URC_SQ_VCCP	12		
A12	URC_SQ_HDINP2	12		T

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
M26	PR27A	2	RDQS27	T (LVDS)*	PR37A	2	RDQS37	T (LVDS)*	
L30	PR26B	2	RDQ27	C	PR36B	2	RDQ37	C	
GNDIO	GNDIO2	-			GNDIO2	-			
L29	PR26A	2	RDQ27	T	PR36A	2	RDQ37	T	
L28	PR25B	2	RDQ27	C (LVDS)*	PR35B	2	RDQ37	C (LVDS)*	
L27	PR25A	2	RDQ27	T (LVDS)*	PR35A	2	RDQ37	T (LVDS)*	
H29	PR24B	2	RDQ27	C	PR34B	2	RDQ37	C	
VCCIO	VCCIO2	2			VCCIO2	2			
G29	PR24A	2	RDQ27	T	PR34A	2	RDQ37	T	
L22	PR23B	2	RDQ27	C (LVDS)*	PR33B	2	RDQ37	C (LVDS)*	
M22	PR23A	2	RDQ27	T (LVDS)*	PR33A	2	RDQ37	T (LVDS)*	
F30	PR21B	2		C	PR31B	2	RDQ28	C	
GNDIO	GNDIO2	-			GNDIO2	-			
F29	PR21A	2		T	PR31A	2	RDQ28	T	
-	-	-			-	-			
-	-	-			-	-			
E30	PR20B	2		C (LVDS)*	PR30B	2	RDQ28	C (LVDS)*	
E29	PR20A	2		T (LVDS)*	PR30A	2	RDQ28	T (LVDS)*	
VCCIO	VCCIO2	2			-	-			
L25	PR19B	2		C	PR29B	2	RDQ28	C	
L26	PR19A	2		T	PR29A	2	RDQ28	T	
-	-	-			VCCIO2	2			
H28	PR18B	2		C (LVDS)*	PR28B	2	RDQ28	C (LVDS)*	
J28	PR18A	2		T (LVDS)*	PR28A	2	RDQS28	T (LVDS)*	
G28	PR16B	2		C	PR27B	2	RDQ28	C	
GNDIO	GNDIO2	-			GNDIO2	-			
G27	PR16A	2		T	PR27A	2	RDQ28	T	
L24	NC	-			PR26B	2	RDQ28	C (LVDS)*	
L23	NC	-			PR26A	2	RDQ28	T (LVDS)*	
D30	NC	-			PR25B	2	RDQ28	C	
-	-	-			VCCIO2	2			
D29	NC	-			PR25A	2	RDQ28	T	
K24	NC	-			PR24B	2	RDQ28	C (LVDS)*	
K25	NC	-			PR24A	2	RDQ28	T (LVDS)*	
J27	NC	-			PR22B	2		C	
-	-	-			GNDIO2	-			
K26	NC	-			PR22A	2		T	
K23	PR15B	2		C (LVDS)*	PR21B	2		C (LVDS)*	
K22	PR15A	2		T (LVDS)*	PR21A	2		T (LVDS)*	
J22	PR14B	2		C	PR20B	2		C	
VCCIO	VCCIO2	-			VCCIO2	2			
J23	PR14A	2		T	PR20A	2		T	
-	-	-			GNDIO2	-			
-	-	-			-	-			
J26	NC	-			PR17B	2	RDQ15	C (LVDS)*	
H26	NC	-			PR17A	2	RDQ15	T (LVDS)*	
H27	NC	-			PR16B	2	RDQ15	C	
G26	NC	-			PR16A	2	RDQ15	T	

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
A21	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12			
A22	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T	
C21	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12			
B19	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C	
B18	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12			
A19	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T	
C18	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12			
D23	PT73B	1		C	PT82B	1		C	
GNDIO	GNDIO1	-			GNDIO1	-			
E21	PT73A	1		T	PT82A	1		T	
D26	PT72B	1		C	PT81B	1		C	
E26	PT72A	1		T	PT81A	1		T	
E23	PT71B	1		C	PT80B	1		C	
-	-	-			VCCIO1	1			
G22	PT71A	1		T	PT80A	1		T	
VCCIO	VCCIO1	1			-	-			
D22	PT70B	1		C	PT79B	1		C	
F21	PT70A	1		T	PT79A	1		T	
G18	PT69B	1		C	PT78B	1		C	
H18	PT69A	1		T	PT78A	1		T	
D20	PT68B	1		C	PT77B	1		C	
GNDIO	GNDIO1	-			GNDIO1	-			
D21	PT68A	1		T	PT77A	1		T	
E20	PT67B	1		C	PT76B	1		C	
E19	PT67A	1		T	PT76A	1		T	
D19	PT66B	1		C	PT75B	1		C	
VCCIO	VCCIO1	1			VCCIO1	1			
E18	PT66A	1		T	PT75A	1		T	
D18	PT65B	1		C	PT74B	1		C	
C17	PT65A	1		T	PT74A	1		T	
A17	PT64B	1		C	PT73B	1		C	
B17	PT64A	1		T	PT73A	1		T	
GNDIO	GNDIO1	-			GNDIO1	-			
VCCIO	VCCIO1	1			VCCIO1	1			
J18	NC	-			PT66B	1		C	
J19	NC	-			PT66A	1		T	
H17	NC	-			PT65B	1		C	
J17	NC	-			PT65A	1		T	
F18	NC	-			PT64B	1		C	
F17	NC	-			PT64A	1		T	
-	-	-			GNDIO1	-			
A16	PT54B	1		C	PT63B	1		C	
B16	PT54A	1		T	PT63A	1		T	
G17	PT53B	1		C	PT62B	1		C	
G16	PT53A	1		T	PT62A	1		T	
VCCIO	VCCIO1	1			VCCIO1	1			
H16	PT52B	1		C	PT61B	1		C	
F16	PT52A	1		T	PT61A	1		T	

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AA1	PL81A	6	LDQS81	T (LVDS)*
GNDIO	GNDIO6	-		
AA2	PL81B	6	LDQ81	C (LVDS)*
Y3	PL82A	6	LDQ81	T
AB1	PL82B	6	LDQ81	C
VCCIO	VCCIO6	6		
Y9	PL83A	6	LDQ81	T (LVDS)*
Y8	PL83B	6	LDQ81	C (LVDS)*
Y7	PL84A	6	LDQ81	T
AA7	PL84B	6	LDQ81	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
AB2	PL95A	6	LDQ99	T (LVDS)*
AB3	PL95B	6	LDQ99	C (LVDS)*
AA5	PL96A	6	LDQ99	T
AA6	PL96B	6	LDQ99	C
AB4	PL97A	6	LDQ99	T (LVDS)*
VCCIO	VCCIO6	6		
AB5	PL97B	6	LDQ99	C (LVDS)*
AA8	PL98A	6	LDQ99	T
AA9	PL98B	6	LDQ99	C
AC1	PL99A	6	LLM0_GPLLT_IN_A**/LDQS99	T (LVDS)*
GNDIO	GNDIO6	-		
AC2	PL99B	6	LLM0_GPLLC_IN_A**/LDQ99	C (LVDS)*
AC4	PL100A	6	LLM0_GPLLT_FB_A/LDQ99	T
AC3	PL100B	6	LLM0_GPLLC_FB_A/LDQ99	C
VCCIO	VCCIO6	6		
AC7	PL101A	6	LLM0_GDLLT_IN_A**/LDQ99	T (LVDS)*
AC6	PL101B	6	LLM0_GDLLC_IN_A**/LDQ99	C (LVDS)*
AC5	PL102A	6	LLM0_GDLLT_FB_A/LDQ99	T
AD3	PL102B	6	LLM0_GDLLC_FB_A/LDQ99	C
GNDIO	GNDIO6	-		
AB8	LLM0_PLLCAP	6		
AD2	PL104A	6		T
AD1	PL104B	6		C
AE2	TCK	-		
AE1	TDI	-		
AF2	TMS	-		
AF1	TDO	-		
AG1	VCCJ	-		
AH1	LLC_SQ_VCCR3	14		
AK2	LLC_SQ_HDINP3	14		T
AJ1	LLC_SQ_VCCIB3	14		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AG2	PB34A	5	BDQ33	T
AG3	PB34B	5	BDQ33	C
AD13	PB35A	5	BDQ33	T
VCCIO	VCCIO5	5		
AC13	PB35B	5	BDQ33	C
AE14	PB36A	5	BDQ33	T
AC14	PB36B	5	BDQ33	C
AF3	PB37A	5	BDQ33	T
GNDIO	GNDIO5	-		
AF4	PB37B	5	BDQ33	C
-	-	-		
AG4	PB38A	5	BDQ42	T
AG5	PB38B	5	BDQ42	C
GNDIO	GNDIO5	-		
-	-	-		
AD11	PB48A	5	BDQ51	T
AF13	PB48B	5	BDQ51	C
AF12	PB49A	5	BDQ51	T
VCCIO	VCCIO5	5		
AD14	PB49B	5	BDQ51	C
AG8	PB50A	5	BDQ51	T
AF8	PB50B	5	BDQ51	C
AE15	PB51A	5	BDQS51****	T
GNDIO	GNDIO5	-		
-	-	-		
AC15	PB51B	5	BDQ51	C
VCCIO	VCCIO5	5		
GNDIO	GNDIO5	-		
AD15	PB56A	5	BDQ60	T
AF15	PB56B	5	BDQ60	C
AG10	PB57A	5	BDQ60	T
AG9	PB57B	5	BDQ60	C
AH14	PB58A	5	BDQ60	T
AG12	PB58B	5	BDQ60	C
VCCIO	VCCIO5	5		
AG15	PB59A	5	BDQ60	T
AG13	PB59B	5	BDQ60	C
GNDIO	GNDIO5	-		
AF16	PB60A	5	BDQS60	T
AH15	PB60B	5	BDQ60	C
AC16	PB61A	5	VREF2_5/BDQ60	T
AE16	PB61B	5	VREF1_5/BDQ60	C
AG11	PB62A	5	PCLKT5_0/BDQ60	T

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K11	NC	-			NC	-		
K12	NC	-			NC	-		
K13	NC	-			NC	-		
K23	NC	-			NC	-		
K24	NC	-			NC	-		
K25	NC	-			NC	-		
K26	NC	-			NC	-		
L11	NC	-			NC	-		
L12	NC	-			NC	-		
L13	NC	-			NC	-		
L14	NC	-			NC	-		
L21	NC	-			NC	-		
L22	NC	-			NC	-		
L23	NC	-			NC	-		
L24	NC	-			NC	-		
L25	NC	-			NC	-		
L26	NC	-			NC	-		
M11	NC	-			NC	-		
M24	NC	-			NC	-		
M25	NC	-			NC	-		
M6	NC	-			NC	-		
M8	NC	-			NC	-		
N10	NC	-			NC	-		
N11	NC	-			NC	-		
P10	NC	-			NC	-		
P25	NC	-			NC	-		
P26	NC	-			NC	-		
R9	NC	-			NC	-		
T11	NC	-			NC	-		
U11	NC	-			NC	-		
W11	NC	-			NC	-		
Y10	NC	-			NC	-		
Y11	NC	-			NC	-		
R15	VCCPLL	-			VCCPLL	-		
R20	VCCPLL	-			VCCPLL	-		
Y15	VCCPLL	-			VCCPLL	-		
Y20	VCCPLL	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70, and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVC MOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
April 2008	03.1	Pinout Information	Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
June 2008	03.2	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
		Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		Clarification of the operation of the secondary clock regions.	
August 2008	03.3	DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
		Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPI _m Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t _{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.